

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-15 (withdrawn)

16. (Original) Sputter target comprising a face area of target material to be sputtered onto a desired substrate, said target material being substantially free of inclusions in said target material of the size of 800  $\mu\text{m}$  and greater.

17. (Original) Sputter target as recited in claim 16 wherein said target material includes a sputter track having a sputter track area adapted for increased consumption of said target material thereat during sputtering, said sputter track being substantially free of inclusions therein of the size of 400  $\mu\text{m}$  and greater.

Claims 18-24 (withdrawn)

25. (New) Sputter target as recited in claim 17, wherein said sputter target is an alloy mixture comprising aluminum or aluminum alloy and an amount of Si therein present in an amount of about 0.01 – 2.00 wt%.

26. (New) Sputter target as recited in claim 25 further comprising Cu present in an amount of about 0.01 – 3.00 wt%.

27. (New) Sputter target comprising a face area of target material to be sputtered onto a desired substrate, said target material being substantially free of inclusions in said target material of the size of 800  $\mu\text{m}$  and greater and wherein said target material includes a sputter track having a sputter track area adapted for increased consumption of said target material thereat during sputtering, said sputter track being substantially free of inclusions therein of the size of 400  $\mu\text{m}$  and greater.